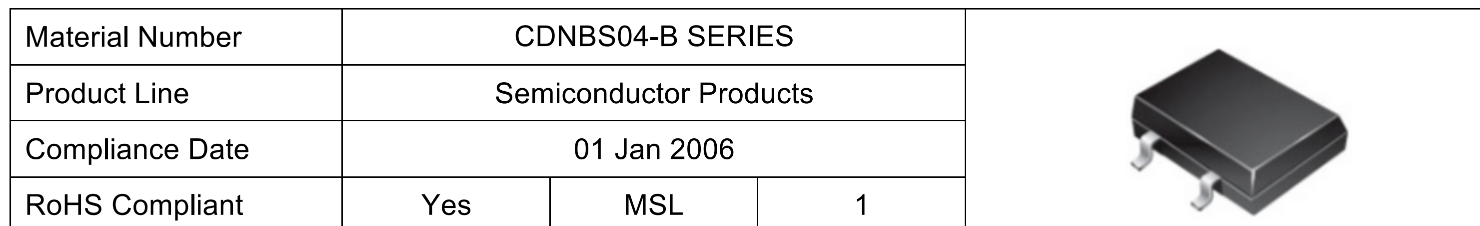
MATERIAL DECLARATION SHEET



Material Number	CDNBS04-B SERIES		
Product Line	Semiconductor Products		
Compliance Date	01 Jan 2006		
RoHS Compliant	Yes	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silica compound	3.25	Silicon	7440-21-3	96.5%	2.50%	2.60%
				Lead*	7439-92-1	2.5%	0.07%	
				Nickel	7440-02-0	1.0%	0.03%	
2	Solder Paste	High-melting point solder	11.25	Lead*	7439-92-1	92.5%	8.32%	9.00%
				Tin	7440-31-5	5.0%	0.45%	
				Silver	7440-22-4	2.5%	0.23%	
3	Lead frame &clip	Copper Alloy	40.19	Copper	7440-50-8	99.95%	32.14%	32.15%
				Zinc	7440-66-6	0.004%	0.00%	
				Iron	7439-89-6	0.010%	0.00%	
				Phosphorus	7723-14-0	0.034%	0.01%	
4	Epoxy material	Epoxy molding compound	69.06	Silica	14808-60-7	70%	38.67%	55.25%
				Epoxy resin	29690-82-2	15%	8.29%	
				Phenol-formaldehyde polymer	9003-35-4	10.0%	5.53%	
				Antimony trioxide	1309-64-4	2.5%	1.38%	
				Bisphenol A diglycidyl ether	40039-93-8	2.5%	1.38%	
5	Plating cover	Sn plating cover	1.25	Tin	7440-31-5	99.5%	1.00%	1.00%
		Total weight	125					

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society

This Document was updated on: 2015-4-27

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. * 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead)
   7(c)-I.Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society